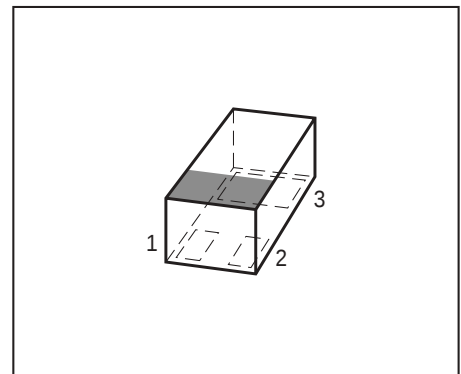


NPN Silicon RF Transistor*

- For low noise, high-gain amplifiers up to 2 GHz
- For linear broadband amplifiers
- $f_T = 8 \text{ GHz}$, $F = 1 \text{ dB}$ at 900 MHz
- * Short term description



ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Type	Marking	Pin Configuration			Package
BFR193L3	RC	1 = B	2 = E	3 = C	TSLP-3-1

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	12	V
Collector-emitter voltage	V_{CES}	20	
Collector-base voltage	V_{CBO}	20	
Emitter-base voltage	V_{EBO}	2	
Collector current	I_C	80	mA
Base current	I_B	10	
Total power dissipation ¹⁾ $T_S \leq 95^\circ\text{C}$	P_{tot}	580	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Ambient temperature	T_A	-55 ... 150	
Storage temperature	T_{stg}	-55 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ²⁾	R_{thJS}	tbd	K/W

¹⁾ T_S is measured on the collector lead at the soldering point to the pcb

²⁾ For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 1\text{ mA}, I_B = 0$	$V_{(BR)CEO}$	12	-	-	V
Collector-emitter cutoff current $V_{CE} = 20\text{ V}, V_{BE} = 0$	I_{CES}	-	-	100	μA
Collector-base cutoff current $V_{CB} = 10\text{ V}, I_E = 0$	I_{CBO}	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 1\text{ V}, I_C = 0$	I_{EBO}	-	-	1	μA
DC current gain- $I_C = 30\text{ mA}, V_{CE} = 8\text{ V}, \text{ pulse measured}$	h_{FE}	70	100	140	-

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

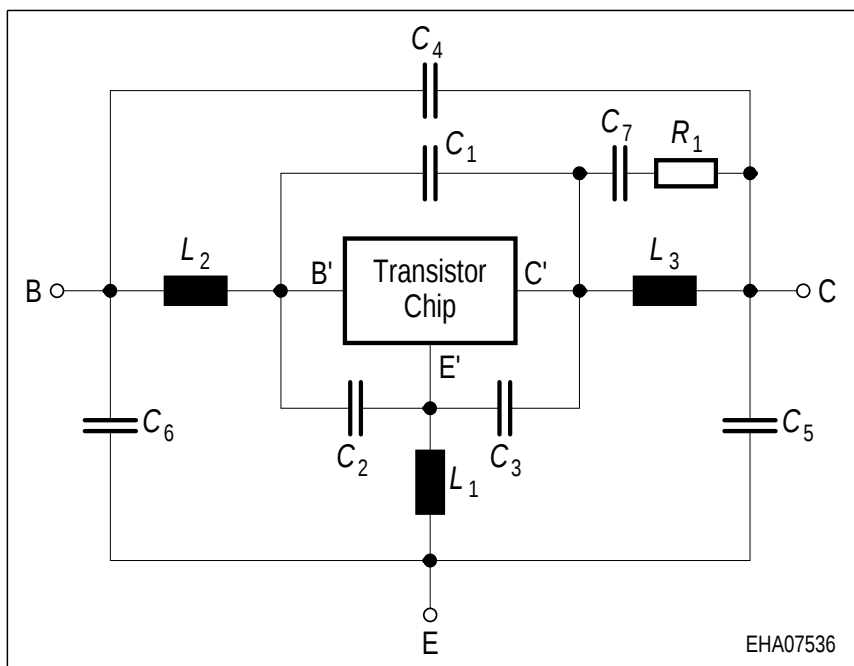
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Transition frequency $I_C = 50\text{ mA}$, $V_{CE} = 8\text{ V}$, $f = 500\text{ MHz}$	f_T	6	8	-	GHz
Collector-base capacitance $V_{CB} = 10\text{ V}$, $f = 1\text{ MHz}$, $V_{BE} = 0$, emitter grounded	C_{cb}	-	0.63	0.9	pF
Collector emitter capacitance $V_{CE} = 10\text{ V}$, $f = 1\text{ MHz}$, $V_{BE} = 0$, base grounded	C_{ce}	-	0.22	-	
Emitter-base capacitance $V_{EB} = 0.5\text{ V}$, $f = 1\text{ MHz}$, $V_{CB} = 0$, collector grounded	C_{eb}	-	2.25	-	
Noise figure $I_C = 10\text{ mA}$, $V_{CE} = 8\text{ V}$, $Z_S = Z_{Sopt}$, $f = 900\text{ MHz}$ $I_C = 10\text{ mA}$, $V_{CE} = 8\text{ V}$, $Z_S = Z_{Sopt}$, $f = 1.8\text{ GHz}$	F	- -	1 1.6	- -	dB
Power gain, maximum available ¹⁾ $I_C = 30\text{ mA}$, $V_{CE} = 8\text{ V}$, $Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$, $f = 900\text{ MHz}$ $I_C = 30\text{ mA}$, $V_{CE} = 8\text{ V}$, $Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$, $f = 1.8\text{ GHz}$	G_{ma}	- -	19 12.5	- -	
Transducer gain $I_C = 30\text{ mA}$, $V_{CE} = 8\text{ V}$, $Z_S = Z_L = 50\Omega$, $f = 900\text{ MHz}$ $I_C = 30\text{ mA}$, $V_{CE} = 8\text{ V}$, $Z_S = Z_L = 50\Omega$, $f = 1.8\text{ GHz}$	$ S_{21e} ^2$	- -	14.5 9	- -	

$$^1G_{ma} = |S_{21} / S_{12}| (k - (k^2 - 1)^{1/2})$$

SPICE Parameter (Gummel-Poon Model, Berkley-SPICE 2G.6 Syntax):
Transistor Chip Data:

IS =	0.2738	fA	BF =	125	-	NF =	0.95341	-
VAF =	24	V	IKF =	0.26949	A	ISE =	10.627	fA
NE =	1.935	-	BR =	14.267	-	NR =	1.4289	-
VAR =	3.8742	V	IKR =	0.037925	A	ISC =	0.037409	fA
NC =	0.94371	-	RB =	1.8368	Ω	IRB =	0.91763	mA
RBM =	1	Ω	RE =	0.76534	-	RC =	0.11938	Ω
CJE =	1.1824	fF	VJE =	0.70276	V	MJE =	0.48654	-
TF =	18.828	ps	XTF =	0.69477	-	VTF =	0.8	V
ITF =	0.96893	mA	PTF =	0	deg	CJC =	935.03	fF
VJC =	1.1828	V	MJC =	0.30002	-	XCJC =	0.053563	-
TR =	1.0037	ns	CJS =	0	fF	VJS =	0.75	V
MJS =	0	-	NK =	0	-	EG =	1.11	eV
XTI =	3	-	FC =	0.72063		TNOM	300	K

All parameters are ready to use, no scaling is necessary. Extracted on behalf of Infineon Technologies AG by:
Institut für Mobil- und Satellitentechnik (IMST)

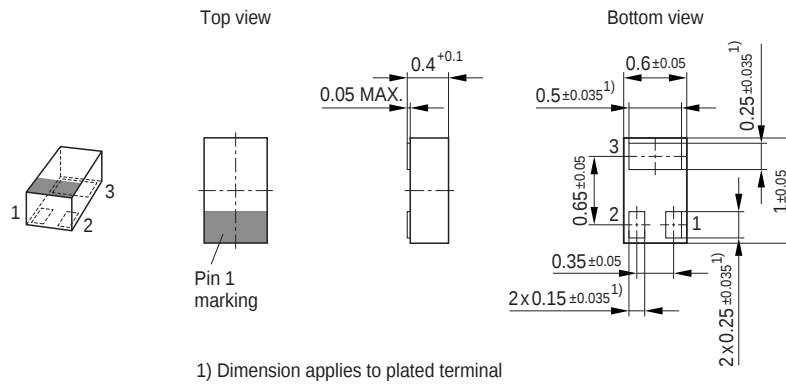
Package Equivalent Circuit:


L_1 =	0.575	nH
L_2 =	0.575	nH
L_3 =	0.275	nH
C_1 =	33	fF
C_2 =	28	fF
C_3 =	131	fF
C_4 =	8	fF
C_5 =	8	fF
C_6 =	24	fF
C_7 =	300	fF
R_1 =	204	Ω

Valid up to 6GHz

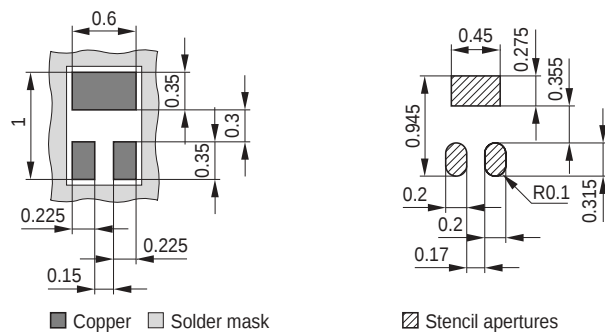
For examples and ready to use parameters
please contact your local Infineon Technologies
distributor or sales office to obtain a Infineon
Technologies CD-ROM or see Internet:
<http://www.infineon.com/silicondiscretes>

Package Outline

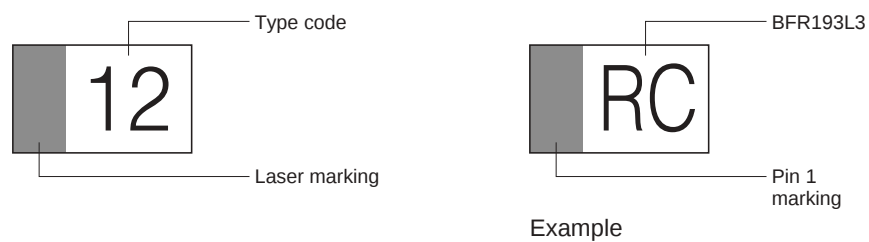


Foot Print

For board assembly information please refer to Infineon website "Packages"

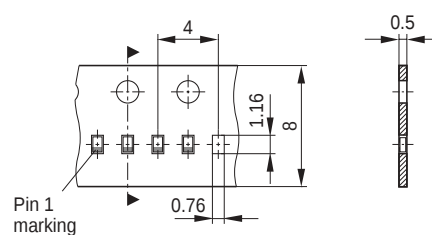


Marking Layout



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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